

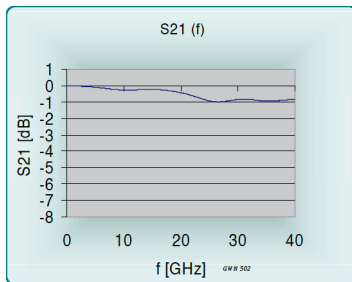


# Long-Life Hi-Frequency Sockets for BGA, LGA, QFN, MLCC, $\mu$ BGA and Bumped Die Devices

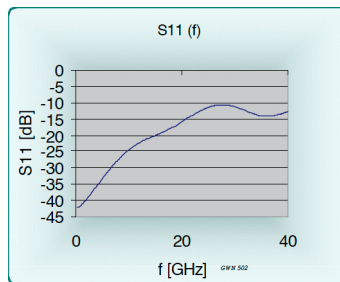
## Ideally Suited for RFIC and Microwave IC Development & Test Interposer Contact System – AR200 and AR300 Series Test Sockets

Announcing significant improvements to our high-performance contact system. Using our proven Interposer Elastomer Technology, the new CORE feature internally controls compression to ensure stability with extremely low resistance values and much longer contact element life. (See Interposer Contact System Life on following page).

Low interconnect parasitics make these sockets an ideal choice for device characterization or high-volume production testing of devices, such as power amplifiers, mixers, highly integrated RF ICs, and microwave devices.



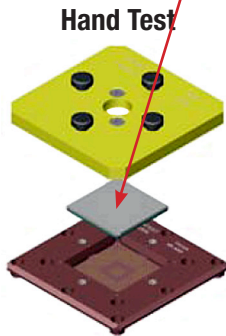
Insertion Loss of -1dB @ 40GHz



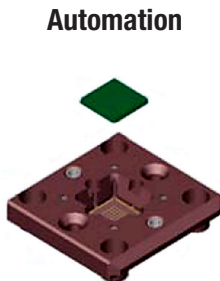
Return Loss of -15dB @ 22GHz

Interposer contact system with very short interconnects (available in 1.0mm or 0.6mm thickness) enhance adjacent channel power and noise sensitivity measurements.

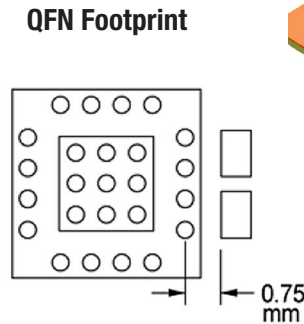
**FULL-ARRAY SHOWN AS AN EXAMPLE; YOUR SPECIFIC DEVICE PATTERN/FOOTPRINT WILL BE SUPPLIED WHEN ORDERED.**



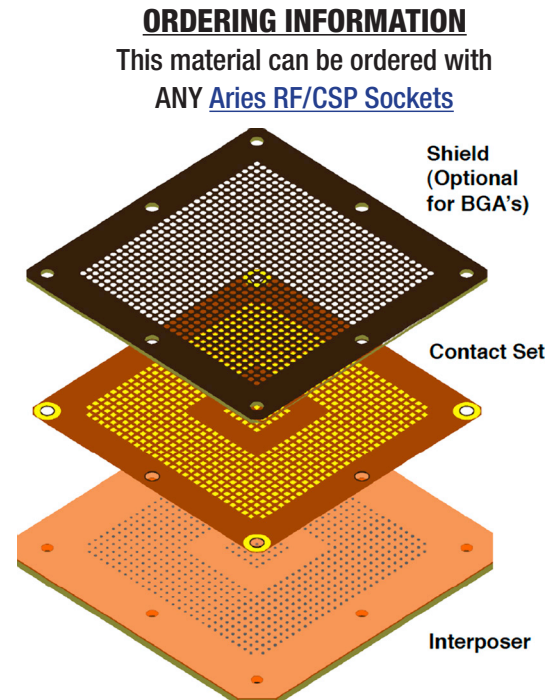
Hand Test



Automation

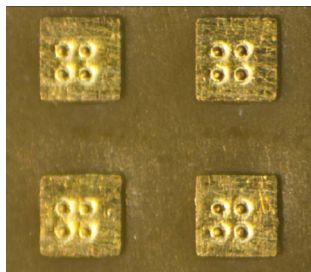


QFN Footprint

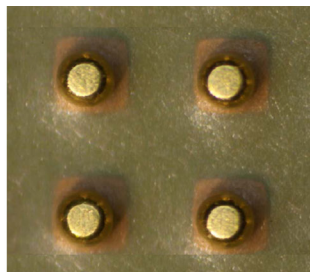


*Interposer footprint lets the PCB designer locate impedance matching network components within 1mm of device pads.*

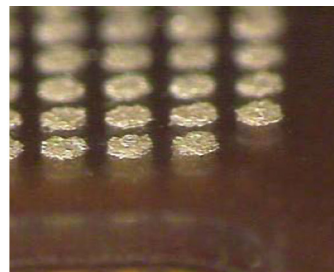
CONTACT SET



Top Side  
Tips Pierce DUT

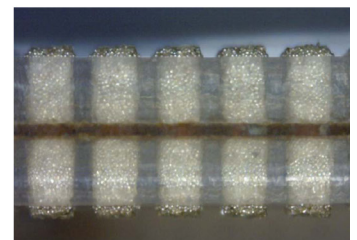


Bottom Side  
Tails Compress Columns



Column Array  
Elastomer Matrix Compliant Buttons

INTERPOSER



Cross Section  
Ag Particles



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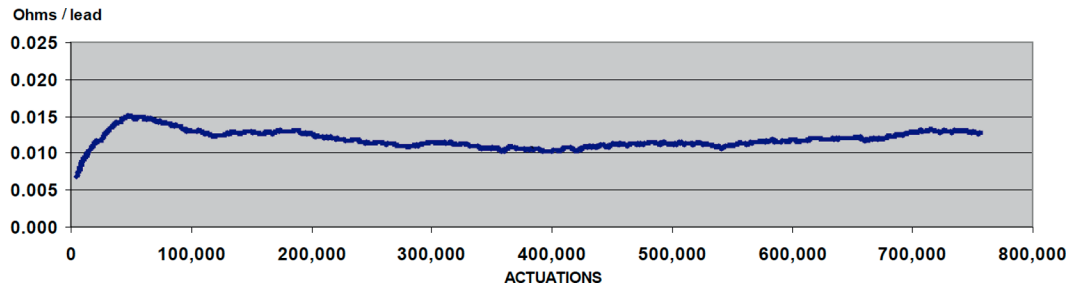
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# Long-Life Hi-Frequency Sockets for BGA, LGA, QFN, MLCC, $\mu$ BGA and Bumped Die Devices

## High-Performance Interposer Contact Technology Suitable for Manual & Automated High-Volume Production Test



### Interposer Contact System Life: QFN 0.5mm Pitch, 1.0mm Full Height

#### AR200 Series: 1.0mm Full Height Specifications

(measured in a 0.5mm pitch environment, GSG)

**Insertion Loss S21:** -1dB @ 40GHz

**Return Loss S11 thru:** -15dB @ 22GHz

**Self Inductance:** 0.33nH

**Mutual Capacitance:** <0.05pF

**Operating Temperature:** -55°C to 155°C

**Contact Resistance:** <25m $\Omega$

**Current Rating:** 4A per lead with a 14°C rise

**Contact Length (compressed):** 1.04mm

**Contact Force/Travel:** 25-45 gf/0.4mm travel

**Contact Set Life:** >2,000,000 insertions

**Interposer Elastomer Life:** >500,000 insertions

#### AR300 Series: 0.6mm Half Height Specifications

(estimated 0.5mm pitch environment, GSG)

**Insertion Loss S21:** -1dB @ >40GHz

**Return Loss S11 thru:** -15dB @ >22GHz

**Self Inductance:** <0.15nH

**Mutual Capacitance:** <0.02pF

**Operating Temperature:** -55°C to 155°C

**Contact Resistance:** <25m $\Omega$

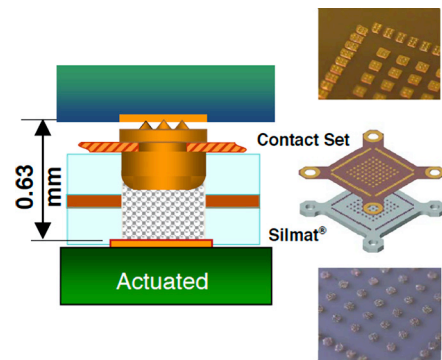
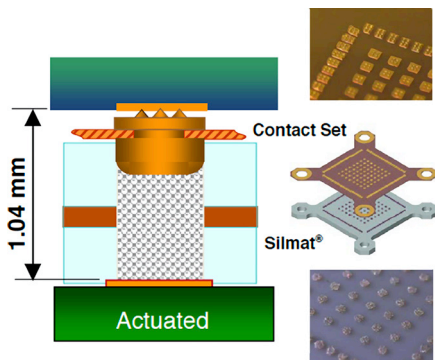
**Current Rating:** 4A per lead with a 14°C rise

**Contact Length (compressed):** 0.63mm

**Contact Force/Travel:** 25-45 gf/0.28mm travel

**Contact Set Life:** >2,000,000 insertions

**Interposer Elastomer Life:** >500,000 insertions



*Interposer Elastomer Conductive Columns, available in 2 Standard Heights with  
Standard & Custom Pitches from 1.27mm to 0.4mm*

See [Assembly and Maintenance Instructions](#)



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